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- Inputs Are TTL-Voltage Compatible
- 3-State Outputs Drive Bus Lines or Buffer Memory Address Registers
- High-Current Outputs Drive up to 15 LSTTL Loads
- Package Options Include Plastic Small-Outline (DW), Shrink Small-Outline (DB), Thin Shrink Small-Outline (PW), and Ceramic Flat (W) Packages, Ceramic Chip Carriers (FK), and Standard Plastic (N) and Ceramic (J) 300-mil DIPs

description

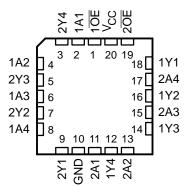
These octal buffers and line drivers are designed specifically to improve both the performance and density of 3-state memory address drivers, clock drivers, and bus-oriented receivers and transmitters. The 'HCT244 are organized as two 4-bit buffers/drivers with separate output-enable (OE) inputs. When OE is low, the device passes noninverted data from the A inputs to the Y outputs. When OE is high, the outputs are in the high-impedance state.

The SN54HCT244 is characterized for operation over the full military temperature range of -55° C to 125°C. The SN74HCT244 is characterized for operation from -40° C to 85°C.

SN54HCT244 J OR W PACKAGE
SN74HCT244DB, DW, N, OR PW PACKAGE
(TOP VIEW)

	•	,	
1OE 1A1 2Y4 1A2 2Y3 1A3 2Y2	5 6 7	14	V _{CC} 2OE 1Y1 2A4 1Y2 2A3 1Y3
1A4	8	13] 2A2
2Y1	9		1Y4
GND	10	11] 2A1

SN54HCT244 . . . FK PACKAGE (TOP VIEW)



FUNCTION TABLE (each buffer/driver)

(each buller/unver)									
INP	UTS	OUTPUT							
OE	Α	Y							
L	Н	Н							
L	L	L							
н	Х	Z							



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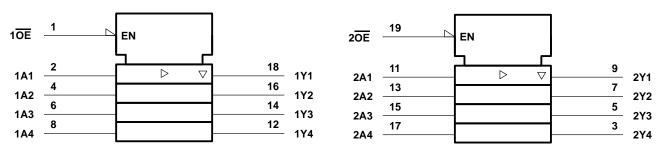
PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



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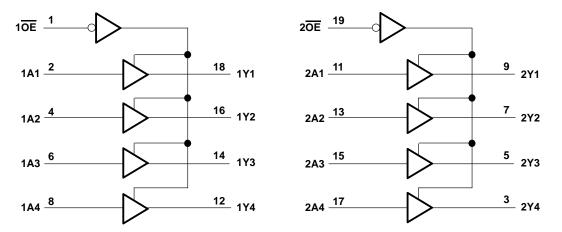
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logic symbol[†]



[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range[‡]

$ \begin{array}{llllllllllllllllllllllllllllllllllll$	nA nA ′W ′W
N package	
Storage temperature range, T _{stg}	

‡ Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

2. The package thermal impedance is calculated in accordance with JESD 51, except for through-hole packages, which use a trace length of zero.



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recommended operating conditions

			SN	54HCT2	44	SN	74HCT2	44	UNIT
			MIN	NOM	MAX	MIN	NOM	MAX	UNIT
Vcc	Supply voltage		4.5	5	5.5	4.5	5	5.5	V
VIH	High-level input voltage	V_{CC} = 4.5 V to 5.5 V	2			2			V
VIL	Low-level input voltage	$V_{CC} = 4.5 V \text{ to } 5.5 V$	0		0.8	0		0.8	V
VI	Input voltage		0		VCC	0		VCC	V
Vo	Output voltage		0		VCC	0		VCC	V
tt	Input transition (rise and fall) time		0		500	0		500	ns
ТА	Operating free-air temperature		-55		125	-40		85	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CO	TEST CONDITIONS		Т	'A = 25°C	;	SN54H	CT244	SN74H	CT244	UNIT
PARAMETER	TEST CO	NDITION3	Vcc	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
Vau		I _{OH} = -20 μA	4.5 V	4.4	4.499		4.4		4.4		V
∨он	VI = VIH or VIL	I _{OH} =6 mA	4.5 V	3.98	4.3		3.7		3.84		v
Ve	VI = VIH or VIL	I _{OL} = 20 μA	4.5 V		0.001	0.1		0.1		0.1	V
VOL		I _{OL} = 6 mA	4.5 V		0.17	0.26		0.4		0.33	v
li	VI = ACC or 0		5.5 V		±0.1	±100		±1000		±1000	nA
IOZ	$V_{O} = V_{CC} \text{ or } 0,$	$V_I = V_{IH} \text{ or } V_{IL}$	5.5 V		±0.01	±0.5		±10		±5	μA
ICC	$V_I = V_{CC} \text{ or } 0,$	IO = 0	5.5 V			8		160		80	μA
∆lcc‡	One input at 0.5 V of Other inputs at 0 or		5.5 V		1.4	2.4		3		2.9	mA
Ci			4.5 V to 5.5 V		3	10		10		10	pF

[†] This is the increase in supply current for each input that is at one of the specified TTL voltage levels rather than 0 V or V_{CC}.

switching characteristics over recommended operating free-air temperature range, $C_L = 50 \text{ pF}$ (unless otherwise noted) (see Figure 1)

PARAMETER	FROM	то	Vee	Тį	ς = 25°C	;	SN54H	CT244	SN74H	CT244	UNIT
PARAMETER	(INPUT)	(OUTPUT)	Vcc	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
• .		Y	4.5 V		15	28		42		35	20
^t pd	A	· · ·	5.5 V		13	25		38		32	ns
+		Y	4.5 V		21	35		53		44	ns
ten	OE		I	5.5 V		19	32		48		40
+	OE	Y	4.5 V		19	35		53		44	ns
^t dis	OE	Ι	5.5 V		18	32		48		40	115
•	V	4.5 V		8	12		18		15		
t		I I	5.5 V		7	11		16		14	ns



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switching characteristics over recommended operating free-air temperature range, $C_L = 150 \text{ pF}$ (unless otherwise noted) (see Figure 1)

PARAMETER	FROM	то	Vee	Т	λ = 25°C	;	SN54H	CT244	SN74H	CT244	UNIT									
FARAMETER	(INPUT)	(OUTPUT)	Vcc	MIN	TYP	MAX	X MIN	MAX	MIN	MAX										
÷ .	А	v	4.5 V		21	45		68		56	20									
^t pd	A	T	I	I	I	I		I	1	·	ľ	5.5 V		18	40		61		51	ns
	OE	v	4.5 V		25	52		79		65										
ten	ÛE	Ŷ	5.5 V		22	47		71		59	ns									
		v	4.5 V		17	42		63		53										
tt		r	5.5 V		14	38		57		48	ns									

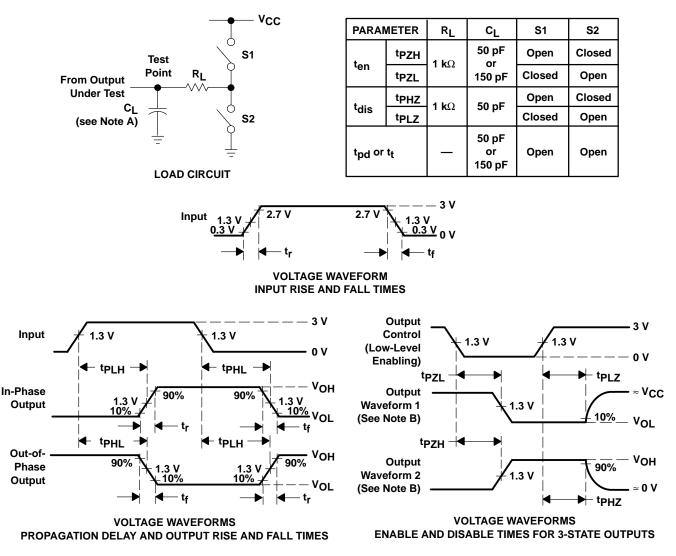
operating characteristics, $T_A = 25^{\circ}C$

	PARAMETER	TEST CONDITIONS	TYP	UNIT
Cpd	Power dissipation capacitance per buffer/driver	No load	40	рF



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PARAMETER MEASUREMENT INFORMATION



- NOTES: A. CL includes probe and test-fixture capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - C. Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, Z_Q = 50 Ω , t_f = 6 ns, t_f = 6 ns.
 - D. The outputs are measured one at a time with one input transition per measurement.
 - E. tpLz and tpHz are the same as tdis.
 - F. t_{P7I} and t_{P7H} are the same as t_{en} .
 - G. tPLH and tPHL are the same as tpd.

Figure 1. Load Circuit and Voltage Waveforms



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